



GE Energy

Functional Testing Specification

Parts & Repair Services
Louisville, KY

LOU-GED-151X1200SA003AF01PA

Test Procedure for a Resistor Assembly DC Link

DOCUMENT REVISION STATUS: Determined by the last entry in the "REV" and "DATE" column

| REV. | DESCRIPTION | SIGNATURE | REV. DATE |
|------|-----------------|-------------|-----------|
| A | Initial release | G. Chandler | 6/18/2011 |
| B | | | |
| C | | | |

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|-----------------------------------|--------------------|--------------------|--|
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| DATE 6/18/2011 | DATE | DATE | DATE 6/18/2011 |

1. SCOPE

1.1 This is a functional testing procedure for a Card.

2. STANDARDS OF QUALITY

2.1 Refer to the current revision of the IPC-A-610 standard for workmanship standards.

3. APPLICABLE DOCUMENTS

3.1 The following document(s) shall form part of this specification to the extent specified herein.
Unless otherwise indicated, the latest issue shall apply.

3.1.1 Check board's electronic folder for more information

4. ENGINEERING REQUIREMENTS

4.1 Equipment Cleaning

4.1.1 Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to site specific SRA's for cleaning guidelines.

4.2 Equipment Inspection

4.2.1 Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:

4.2.1.1 Wires - broken, cracked, or loosely connected

4.2.1.2 Terminal strips / connectors - broken or cracked

4.2.1.3 Components - visually damaged

4.2.1.4 Capacitors - bloated or leaking

4.2.1.5 Solder joints - damaged or cold

4.2.1.6 Circuit board - burned or de-laminated

4.2.1.7 Printed wire runs / Traces - burned or damaged

5. EQUIPMENT REQUIRED

5.1 The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

| Qty | Reference # | Description |
|-----|-------------|------------------------------|
| 1 | | Fluke 87 DMM (or Equivalent) |
| | | |
| | | |

6. Modifications/Upgrades

6.1 None at this time.

7. Testing Process

7.1 Setup

7.1.1 Using figure 1, make the following measurements:

7.1.2 From point A to point B 7.9 ohms +/- 10%.

7.1.3 From point A to point C 9K ohms +/- 10%.

7.1.4 From point A to point D 9K ohms +/- 10%.

7.1.5 From point A to point E 9K ohms +/- 10%.

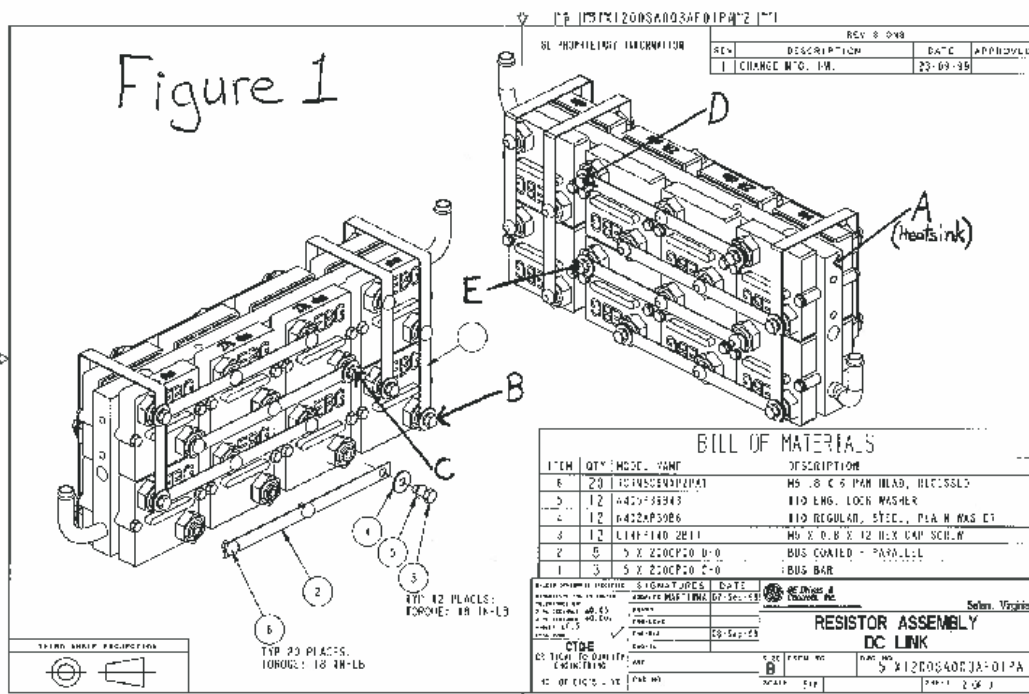


Figure 1

7.2 Pressure test the water cooled heat-sink at 60psi.

7.3 ***TEST COMPLETE***

8. Notes

8.1 None at this time.